

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimension mm(inches)
1	C1,C2	2	1 μ F			Ceramic, 50V, \pm 10%	-	3.2 x 1.6 (1206)
2	Q1,Q2	2		SSM6K513NU	TOSHIBA		UDFN6B	2.0 x 2.0
3	IC1	1		TCK401G	TOSHIBA		WCSP6E	0.8 x 1.2

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